

S/N 10/774,923

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Qing Ma

Examiner: Roy K. Potter

Serial No.: 10/774,923

Group Art Unit: 2822

Filed: February 9, 2004

Docket No.: 884.803US2

Title: DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE HAVING A
MOISTURE BARRIER STRUCTURE

Customer Number: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

This responds to the Office Action mailed on November 28, 2007. Please amend the
above-identified patent application as follows.